

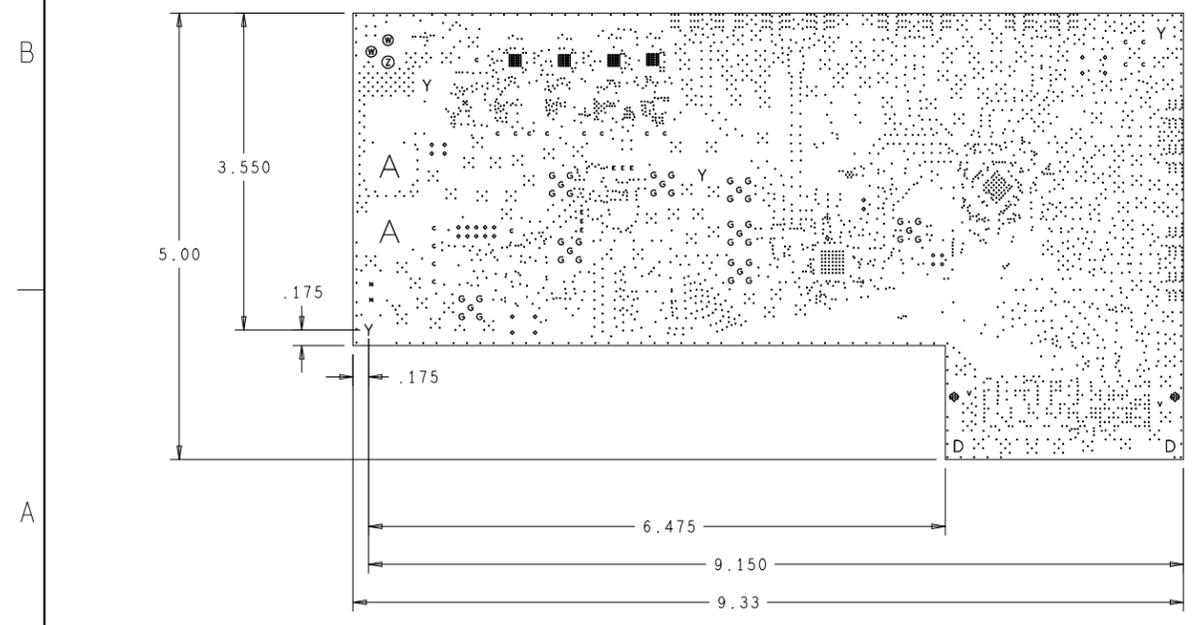
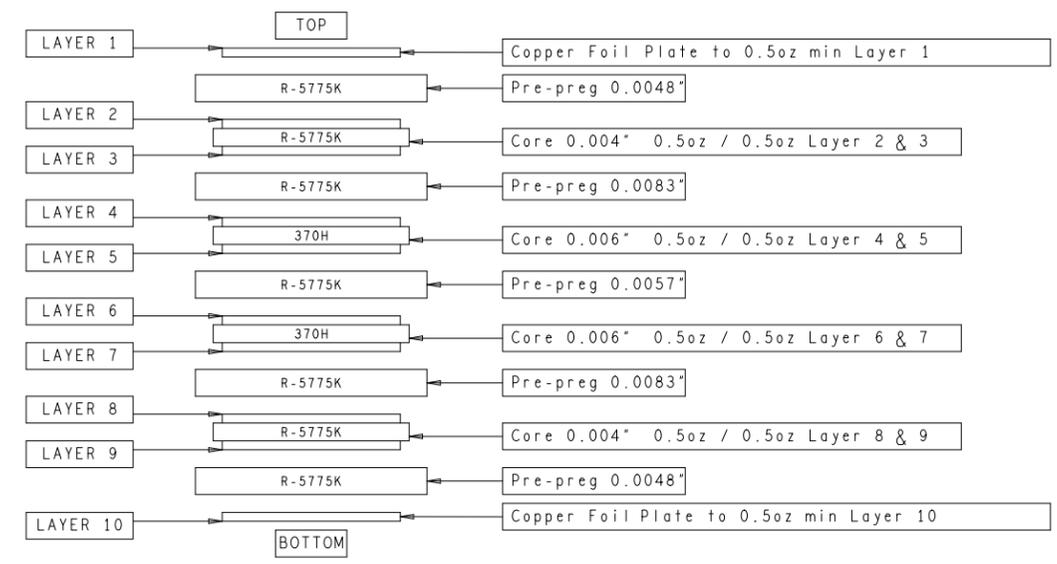
REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

- APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.  
IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.  
IPC-6012B / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD.  
IPC-A-600G / ACCEPTABILITY OF PRINTED BOARDS.
- VIAS, 10 & 12mil HOLES. SIZE APPLY AFTER PLATING. TOLERANCE TO BE +.003/- .010. HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/- .003.
- REGISTRATION TOLERANCE: ARTWORK +/- .002. ALL HOLE CENTERS +/- .005 FROM DIMENSION DATUM.
- MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH. FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
- PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0. MATERIAL: MULTI-LAYER (SEE DETAIL 'A'). SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 +/- 10%
- MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
- SMOBC/IMMERSION GOLD: 2 - 8 uIN OVER 118-236 uIN NICKEL PLATING.
- SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT) COLOR = RED (0.001 TO 002" THICK OVER METAL.
- SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE. REGISTRATION TOLERANCE TO BE +/- .005. INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
- P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
- BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
- BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.

- ALL OUTER LAYERS USING A 8.7MIL TRACE WIDTH SHALL BE 50 OHMS SINGLE ENDED +/- 10%.
- ALL OUTER LAYERS USING A 5.6MIL TRACE WIDTH AND 6.4MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL +/- 10%. ALL INNER LAYERS USING 5MIL TRACE WIDTH AND 7MIL SPACING SHALL BE 100 OHMS DIFFERENTIAL +/- 10%.
- MINIMUM COPPER CONDUCTOR WIDTH IS: 4.5MIL. MINIMUM COPPER CONDUCTOR SPACING IS: 4.5MIL.
- ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
- PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY. MAX REFLOW OF 260 DEGREES C (6 PASSES).
- COPPER TO THE BOARD EDGE IS INTENTIONAL. DO NOT CUT IT BACK.

USE VIASYSTEMS STACKUP PART NUMBER AD58J8X-10



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	10.0	PLATED	3477
•	12.0	PLATED	100
•	20.0	PLATED	4
•	38.0	PLATED	18
•	38.0	PLATED	24
•	40.0	PLATED	6
•	62.0	PLATED	8
•	67.0	PLATED	32
•	106.0	PLATED	2
•	120.0	PLATED	2
Y	125.0	PLATED	4
•	140.0	PLATED	1
A	250.0	PLATED	2
•	39.0	NON-PLATED	2
v	50.0	NON-PLATED	2
D	125.0	NON-PLATED	2

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- +/- .XXX +/- .005 +/-	CONTRACT NO.		TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	FABRICATION DRAWING ADS58J89/ADS54J54 EVM	
DRAWN JV SMITH	10-22-13			
MATERIAL SEE NOTE 5	ENG R PRENTICE	10-22-13	SIZE D	CODE IDENT NO.
FINISH SEE NOTE 7, 8, 9			DRAWING NO.	REV. C
DO NOT SCALE DRAWING	SCALE 1: NONE			SHEET 1 OF 1